

Title (en)

LIQUID DISCHARGING APPARATUS AND METHOD FOR MANUFACTURING LIQUID DISCHARGING APPARATUS

Title (de)

FLÜSSIGKEITSABFÜHRVORRICHTUNG UND VERFAHREN ZUR HERSTELLUNG DER FLÜSSIGKEITSABFÜHRVORRICHTUNG

Title (fr)

APPAREIL DE DÉCHARGE LIQUIDE ET PROCÉDÉ DE FABRICATION DE L'APPAREIL DE DÉCHARGE LIQUIDE

Publication

**EP 1769918 A4 20080924 (EN)**

Application

**EP 05751205 A 20050616**

Priority

- JP 2005011044 W 20050616
- JP 2004179309 A 20040617

Abstract (en)

[origin: EP1769918A1] There is provided a head including a chip 10 that has a semiconductor substrate 11, heating elements 12 disposed on the semiconductor substrate 11, coating layers 14 disposed on the semiconductor substrate 11 and having nozzles 14a arranged in regions above the respective heating elements 12, and individual channels 14b each communicating with the outside and the region above the corresponding heating element 12, wherein the semiconductor substrate 11 does not have a through hole communicating with each individual channel 14b; a ink feed member 21 having a common channel 21b, the ink feed member 21 being bonded to the chip 10 in such a manner that the common channel 21b communicates with the individual channels 14b; and a top 22 disposed on the chip 10 and the ink feed member 21 so as to seal the opening of the common channel 21b.

IPC 8 full level

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Citation (search report)

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